

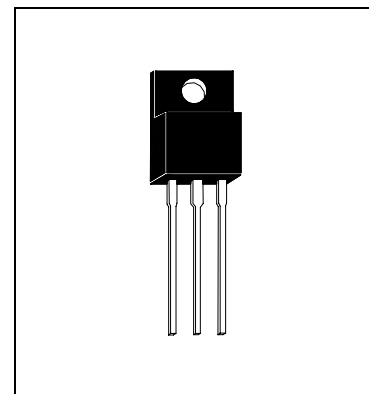


HSBF861

PNP EPITAXIAL PLANAR TRANSISTOR

Description

Low frequency power amplifier.
Color TV vertical deflection output.



Absolute Maximum Ratings (Ta=25°C)

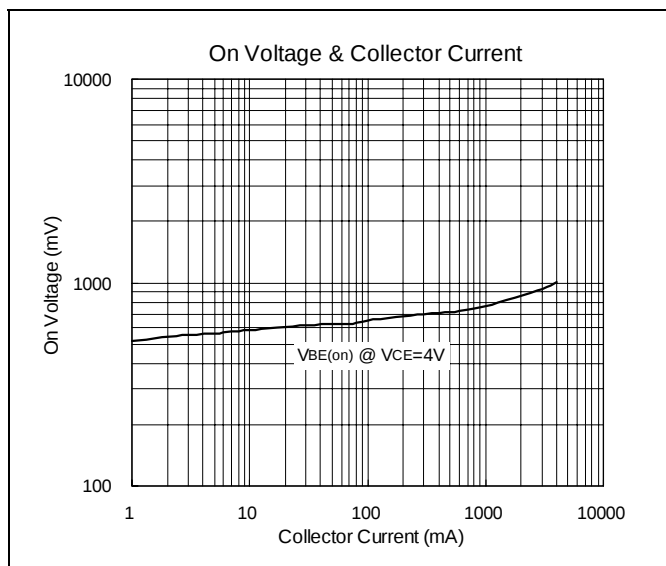
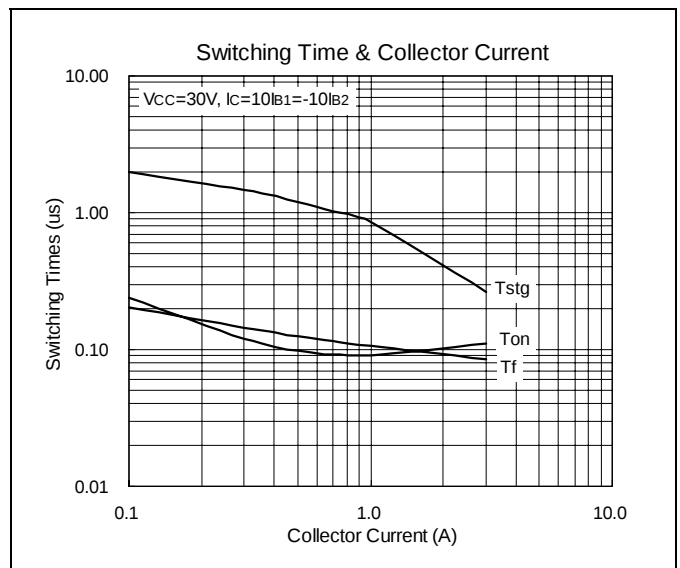
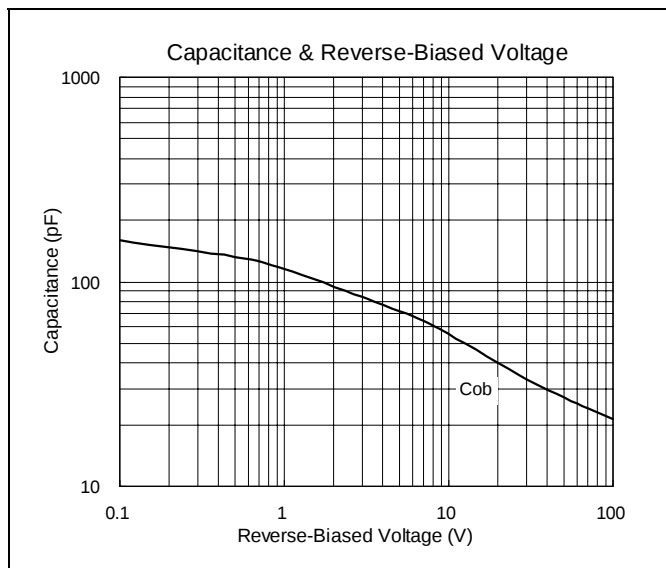
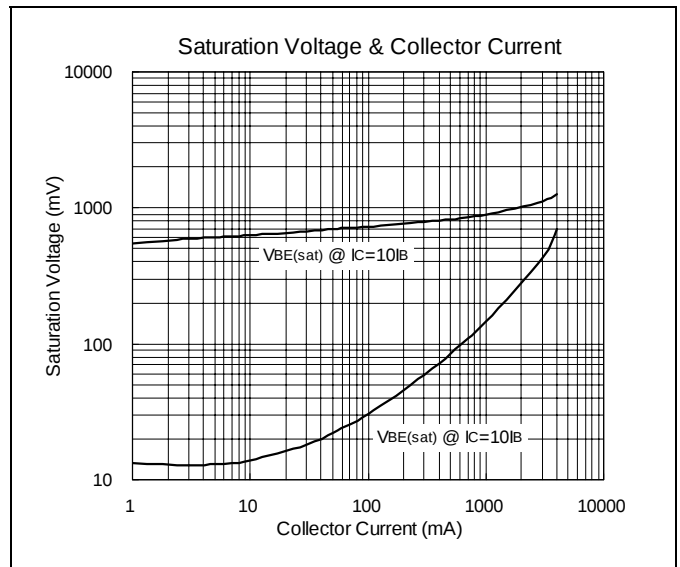
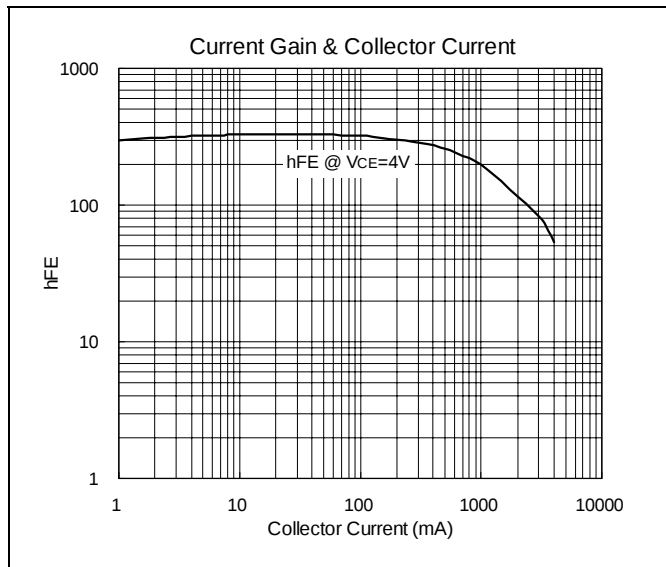
- Maximum Temperatures
Storage Temperature -55~+150°C
Junction Temperature +150°C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 200 V
BVCEO Collector to Emitter Voltage 150 V
BVEBO Emitter to Base Voltage 6 V
IC Collector Current 2 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	200	-	-	V	IC=10uA
BVCEO	150	-	-	V	IC=50mA
BVEBO	6	-	-	V	IE=5mA
ICBO	-	-	1	uA	VCB=120V
VCE(sat)	-	-	3	V	IC=500mA, IB=50mA
VBE(on)	-	-	1	V	IC=50mA, VCE=4V
hFE1	60	-	200		IC=50mA, VCE=4V
hFE2	60	-	-		IC=500mA, VCE=10V
Cob	-	30	-	pF	VCB=100V, IE=5mA

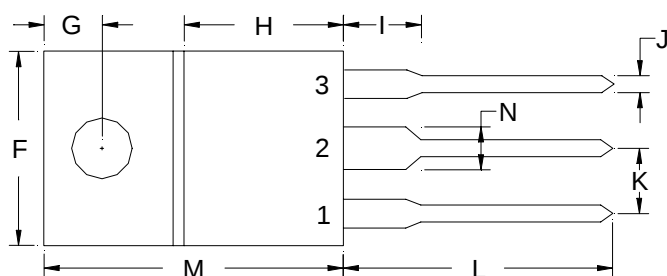
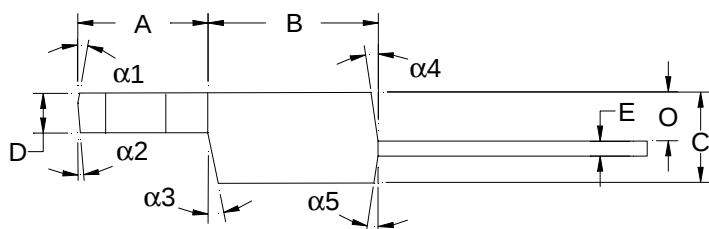


Characteristics Curve



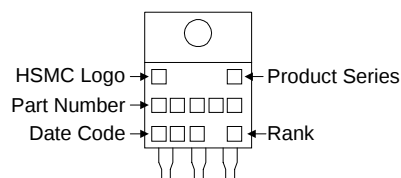


TO-220FP Dimension



3-Lead TO-220FP Plastic Package
HSMC Package Code : F

Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2480	0.2520	6.30	6.40	K	-	*0.1004	-	*2.55
B	0.3386	0.3425	8.60	8.70	L	0.5118	0.5906	13.00	15.00
C	0.1673	0.1870	4.25	4.75	M	0.5886	0.5925	14.95	15.05
D	0.1043	0.1083	2.65	2.75	N	-	*0.0669	-	*1.70
E	0.0230	0.0242	0.58	0.61	O	0.1098	0.1114	2.79	2.83
F	0.3980	0.4039	10.11	10.26	1	-	-2°	-	*2°
G	0.1083	0.1122	2.75	2.85	2	-	*5°	-	*5°
H	0.3386	0.3425	8.60	8.70	3	-	*15°	-	*15°
I	-	*0.1496	-	*3.80	4	-	*5°	-	*5°
J	-	*0.0236	-	*0.60	5	-	*5°	-	*5°

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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